# TOSHIBA DIODE SILICON EPITAXIAL SCHOTTKY BARRIER TYPE

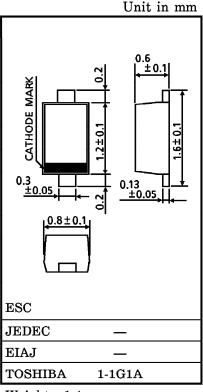
# 155389

### HIGH SPEED SWITCHING APPLICATION

- Small Package
- Low Forward Voltage :  $V_F = 0.23V (TYP.)$  @ $I_F = 5mA$

## MAXIMUM RATINGS (Ta = 25°C)

100 0 0 10 10 11 10 11 10 5 (14 - 25 C)			
CHARACTERISTIC	SYMBOL	RATING	UNIT
Maximum (Peak) Reverse Voltage	$v_{RM}$	15	V
Reverse Voltage	$v_{\mathbf{R}}$	10	V
Maximum (Peak) Forward Current	$I_{FM}$	200	mA
Average Forward Current	IO	100	mA
Surge Current (10ms)	$I_{FSM}$	1	Α
Power Dissipation	P%	150	mW
Junction Temperature	$T_{j}$	125	°C
Storage Temperature Range	$\mathrm{T_{stg}}$	-55~125	°C
Operating Temperature Range	${ m T_{opr}}$	-40~100	°C



Weight: 1.4mg

# ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	$V_{\mathrm{F}(1)}$	$I_F = 1mA$	1	0.18	_	v
	$V_{F(2)}$	$I_{\mathbf{F}} = 5 \text{mA}$		0.23	0.30	
	$V_{F(3)}$	$I_{ m F} = 100 { m mA}$		0.35	0.50	
Reverse Current	${ m I}_{ m R}$	$V_R = 10V$	1		20	$\mu$ <b>A</b>
Total Capacitance	$\mathrm{c_{T}}$	$V_R$ =0, f=1MHz	_	20	40	рF

### **EQUIVALENT CIRCUIT (TOP VIEW)**

#### MARKING





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<sup>\*</sup> Mounted on a glass epoxy circuit board of 20×20mm Pad dimension of 4×4mm.

